

300mm Fully-Automatic Multifunction Wafer Mounter

RAD-2510F/12S2



Outline

– Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:

- UV irradiation to BG Tape
- Alignment
- Wafer mounting
- BG Tape peeling

- Ability to operate in-line with DISCO Corporation's DFG8000 series back grinder or DGP8000 series grinder/polisher.

- Corresponds to DBG™ process.

- Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

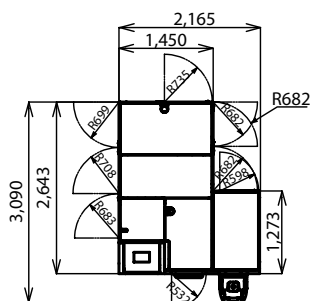
Options

- Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM)
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Dicing Tape In-line Pre-cutting
- DBG™ Process Compatibility
- In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series

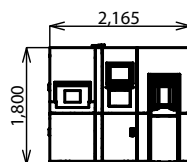
Suitable Tapes

- Dicing tape : Adwill D series, G series
- Dicing die bonding tape : Adwill LE Tape

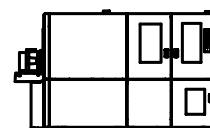
External View



Top View



Front View



Right Side View

Unit: mm



LINTEC Corporation *Linking your dreams*

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